Amendments to the Specification:

Please amend the specification as follows:

Please replace the paragraph starting at page 13, line 6, with the following:

FIG. 6 schematically shows the allocation of a measurement location 22 identified in measurement unit 9 for thin-layer macrometrology to a corresponding measurement location 24 in measurement unit 5 for thin-layer micrometrology. In measurement unit 9 for thin-layer macrometrology, there is found on semiconductor substrate 16 a measurement location 22 at which a certain threshold value is exceeded in terms of thickness fluctuations of the thin layers applied onto semiconductor substrate 16. The corresponding X coordinates and Y coordinates of measurement point 22 are determined and are transferred to computer 15. It is self-evident to one skilled in the art that measurement point 22 can possess a certain extension in terms of area, which is likewise transmitted to computer 15. From computer 15, the corresponding data for measurement point 22 that was identified in measurement unit 9 for thin-layer macrometrology are transferred to measurement unit 5 for thin-layer micrometrology. Semiconductor substrate 16 is appropriately oriented in measurement unit 5 for thin-layer micrometrology so that measurement location 22 identified in measurement unit 9 for thin-layer macrometrology can also be located again. The orientation can be performed, on the one hand, in such a way that semiconductor substrate 16 possesses the same orientation in measurement unit 9 for thin-layer macrometrology and in measurement unit 5 for thin-layer micrometrology. If the orientation of semiconductor substrate 16 in measurement unit 5 for thin-layer micrometrology differs from the orientation of semiconductor substrate 16 in measurement unit 9 for thin-layer macrometrology, measurement location 24 in measurement unit 5 for thin-layer micrometrology can then be located by way of a suitable coordinate transformation. In measurement unit 5 for thin-layer micrometrology, a highly accurate and precise measurement is performed by means of a microphotometer and/or a microellipsometer.